

Lenovo System x 3100 M5 server (5457C5G)

System x 3100 M5 - 1x Xeon E3-1220v3 3.1GHz 8MB 4C 1600 (80W), 4GB, O/B 3.5" HS SAS/SATA, H1110, DVD-ROM, 1x430W HS PSU



Price details:

Price excl. VAT: 1,087.32 €

Eco fees: 0.07 €

VAT 21 %: 228.35 €

Product details:

Product code: 5457C5G

EAN: 5051045189880

Manufacturer: Lenovo

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1,315.74 €

* VAT included

Business-class reliability, performance, and energy efficiency in a compact tower

The new single-socket IBM® System x3100 M5 server provides business-class reliability and performance in a compact tower, optimized for small to medium-sized businesses and distributed environments. Equipped with the latest Intel Xeon E3-1200 v3 processors, USB 3.0 for fast data transfer, 1.35 V low-voltage memory for power savings, 3.5-inch hot-swap SAS hard disk drives (HDDs) for minimized downtime, and four levels of RAID for enhanced data protection, the x3100 M5 brings new levels of performance to your workloads while maximizing energy savings. This efficient tower meets your business needs today and offers upgrade potential when your requirements grow.

Reliability and performance in a flexible, compact tower server

Whether your workloads include basic infrastructure, web server, or file and print, the x3100 M5 delivers. Choose your storage preference from models with four 3.5-inch simple-swap HDD bays, or get the hot-swap versatility of eight 2.5-inch bays or four 3.5-inch hot-swap bays. Standard features include capacity for up to 32 GB of memory, two Gigabit Ethernet ports, and two front-mounted fast USB 3.0 ports, plus multiple internal and external USB 2.0 connections. Business-class reliability features—such as standard RAID, basic light path diagnostics, and optional redundant power supplies and fans—protect your data and facilitate outstanding uptime for your business at great value. And no matter the model, every configuration incorporates IBM quality.

Main specifications:

Processor

Processor frequency:	3.1 GHz
Processor family:	Intel Xeon E3 v3
Processor model:	E3-1220V3
Processor cores:	4
Number of processors installed:	1
Processor cache type:	Smart Cache
Processor cache:	8 MB
System bus rate:	5 GT/s
Processor manufacturer:	Intel
Processor socket:	LGA 1150 (Socket H3)
Processor boost frequency:	3.5 GHz
Processor lithography:	22 nm
Processor threads:	4
Processor operating modes:	64-bit
Stepping:	C0
FSB Parity:	N
Bus type:	DMI
Number of QPI links:	1
Processor codename:	Haswell

Maximum internal memory supported by processor:	32 GB
Memory types supported by processor:	DDR3-SDRAM
Memory clock speeds supported by processor:	1333,1600 MHz
Memory bandwidth supported by processor (max):	25.6 GB/s
Memory channels supported by processor:	Dual
ECC supported by processor:	Y
Execute Disable Bit:	Y
Idle States:	Y
Thermal Monitoring Technologies:	Y
Maximum number of PCI Express lanes:	16
PCI Express configurations:	1x8,1x16,2x4,2x8
Processor package size:	37.5 mm
Supported instruction sets:	AVX 2.0,SSE4.1,SSE4.2
Scalability:	1S
Embedded options available:	N
Thermal solution specification:	PCG 2013D
Graphics & IMC lithography:	22 nm
Thermal Design Power (TDP):	80 W
Processor series:	Intel Xeon E3-1200 v3
Conflict Free processor:	N

Memory

Internal memory:	4 GB
Internal memory type:	DDR3-SDRAM
Maximum internal memory:	32 GB
Memory slots:	4x UDIMM
Memory clock speed:	1600 MHz
ECC:	Y
Memory layout (slots x size):	1 x 4 GB

Storage

Hard drive size:	3.5 "
Hard drive interface:	Serial ATA,Serial Attached SCSI (SAS)
RAID support:	Y
Maximum storage capacity:	16 TB
Hot-Plug support:	Y
Internal drive bays:	4

Graphics

On-board graphics adapter:	N
On-board graphics adapter model:	Not available

Networking

Ethernet LAN:	Y
Wi-Fi:	N

Ports & interfaces

USB 2.0 ports quantity:	4
Ethernet LAN (RJ-45) ports:	2
USB 3.0 (3.1 Gen 1) Type-A ports quantity:	2

Expansion slots

PCI Express x4 (Gen 3.x) slots:	1
PCI Express x8 (Gen 3.x) slots:	1
PCI Express x16 (Gen 3.x) slots:	1
PCI Express slots version:	3.0

Design

Chassis type:	Tower
Optical drive type:	DVD-ROM

Performance

Operating system installed:	N
Compatible operating systems:	Microsoft Windows Server 2012/2008/R2, SBS 2011, Red Hat Enterprise Linux, SUSE Linux, VMware

Processor special features

CPU configuration (max):	1
Intel Rapid Storage Technology:	N
Enhanced Intel SpeedStep Technology:	Y
Intel® Identity Protection Technology (Intel® IPT):	Y
Intel® Wireless Display (Intel® WiDi):	N

Intel Virtualization Technology for Directed I/O (VT-d):	Y
Intel® Anti-Theft Technology (Intel® AT):	Y
Intel® Hyper Threading Technology (Intel® HT Technology):	N
Intel® My WiFi Technology (Intel® MWT):	N
Intel® Turbo Boost Technology:	2.0
Intel® vPro® Technology:	Y
Intel® Quick Sync Video Technology:	N
Intel® InTru® 3D Technology:	N
Intel® Clear Video HD Technology (Intel® CVT HD):	N
Intel® Insider®:	N
Intel Flex Memory Access:	Y
Intel® AES New Instructions (Intel® AES-NI):	Y
Intel Trusted Execution Technology:	Y
Intel Enhanced Halt State:	Y
Intel VT-x with Extended Page Tables (EPT):	Y
Intel Demand Based Switching:	N
Intel® Secure Key:	Y
Intel TSX-NI:	Y
Intel Clear Video Technology:	N
Intel® Clear Video Technology for Mobile Internet Devices (Intel CVT for MID):	N
Intel 64:	Y
Intel Identity Protection Technology version:	1.00
Intel Stable Image Platform Program (SIPP) version:	1.00
Intel Secure Key Technology version:	1.00
Intel Virtualization Technology (VT-x):	Y
Intel TSX-NI version:	1.00
Intel Dual Display Capable Technology:	N
Intel FDI Technology:	N
Intel Fast Memory Access:	Y
Processor ARK ID:	75052

Power

Redundant power supply (RPS) support:	O
Power supply:	430 W
Number of main power supplies:	1

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